

# Global Fan-in Wafer Level Packaging Market Professional Survey Report 2017

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## Abstracts

### Notes:

Production, means the output of Fan-in Wafer Level Packaging

Revenue, means the sales value of Fan-in Wafer Level Packaging

This report studies Fan-in Wafer Level Packaging in Global market, especially in North America, China, Europe, Southeast Asia, Japan and India, with production, revenue, consumption, import and export in these regions, from 2011 to 2015, and forecast to 2021.

This report focuses on top manufacturers in global market, with production, price, revenue and market share for each manufacturer, covering

STATS ChipPAC

STMicroelectronics

TSMC

Texas Instruments

Rudolph Technologies

SEMES

SUSS MicroTec

Ultratech

FlipChip International

IWLPC

By types, the market can be split into

Type I

Type II

Type III

By Application, the market can be split into

CMOS image sensor

Wireless connectivity

Logic and memory IC

MEMS and sensor

Analog and mixed IC

By Regions, this report covers (we can add the regions/countries as you want)

North America

China

Europe

Southeast Asia

Japan

India

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